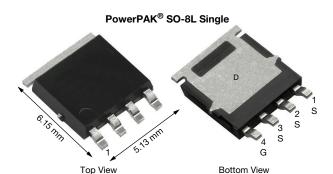
COMPLIANT

HALOGEN



N-Channel 40 V (D-S) 150 °C MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	40				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.00265				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.00360				
Q _g typ. (nC)	23				
I _D (A) ^a	109				
Configuration	Single				

FEATURES

- TrenchFET® Gen IV power MOSFET
- Tuned for the lowest R_{DS}-Q_{oss} FOM
- 100 % R_a and UIS tested

· Synchronous rectification

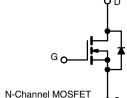
DC/AC inverters

• High power density DC/DC



· Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

FREE APPLICATIONS



ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SiJA58DP-T1-GE3

PARAMETER Drain-source voltage		SYMBOL	LIMIT	UNIT	
		V _{DS}	40	V	
Gate-source voltage		V _{GS}	+20 / -16		
	T _C = 25 °C		109		
Continuous drain current (T _J = 150 °C)	T _C = 70 °C		87.3		
	T _A = 25 °C	I _D	29.3 ^b		
	T _A = 70 °C	1	23.3 b	A	
Pulsed drain current (t = 100 μs)		I _{DM}	I _{DM} 150		
On all and a second of all all all and a second	T _C = 25 °C		51.6		
Continuous source-drain diode current	T _A = 25 °C	ls	3.7 b, c		
Single pulse avalanche current		I _{AS}	30		
Single pulse avalanche energy L = 0.1 mH		E _{AS}	45	mJ	
	T _C = 25 °C		56.8		
Maximum navvar dissination	T _C = 70 °C		36.3	W	
Maximum power dissipation	T _A = 25 °C	P _D	4.1 ^b		
	T _A =70 °C	1	2.6 ^b		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) c			260		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b	t < 10 s	R_{thJA}	25	30	°C/W	
Maximum junction-to-case (drain)	Steady state	R_{thJC}	1.7	2.2		

Notes

- a. $T_C = 25 \,^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- f. Maximum under steady state conditions is 70 °C/W



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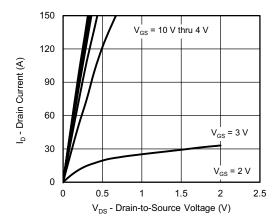
SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT		
Static								
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40	-	-	V		
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 10 mA	-	24	-	ma\//0/		
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-5.5	-	mV/°C		
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1	-	2.4	V		
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = +20 / -16 \text{ V}$	-	-	100	nA		
Zana mata walta na alumin awamant	,	V _{DS} = 40 V, V _{GS} =0 V	-	-	1	μA		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 70 °C	-	-	15			
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	30	-	-	Α		
Data and a state and all and a	Б	V _{GS} = 10 V, I _D = 15 A	-	0.00220	0.00265	Ω		
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	-	0.00300	0.00360			
Forward transconductance a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A	-	125	-	S		
Dynamic ^b			-1		•			
Input capacitance	C _{iss}		-	3750	-			
Output capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	560	-	pF		
Reverse transfer capacitance	C _{rss}		-	72	-			
	Q _g	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	50	75	nC		
Total gate charge		50 / de / 5	-	23	35			
Gate-source charge	Q _{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$	-	10.3	-			
Gate-drain charge	Q _{qd}		-	4.3	-			
Output charge	Q _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	-	24	-			
Gate resistance	R_g	f = 1 MHz	0.5	1.2	2.4	Ω		
Turn-on delay time	t _{d(on)}		-	10	20			
Rise time	t _r	$V_{DD} = 20 \text{ V}, \text{ R}_L = 2 \Omega, \text{ I}_D \cong 10 \text{ A},$	-	19	38	1		
Turn-off delay time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	28	56			
Fall time	t _f		-	8	16			
Turn-on delay time	t _{d(on)}		-	22	44	ns		
Rise time	t _r	$V_{DD} = 20 \text{ V}, R_{I} = 2 \Omega, I_{D} \cong 10 \text{ A},$	-	52	100	- - -		
Turn-off delay time	t _{d(off)}	$V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	23	46			
Fall time	t _f		-	10	20			
Drain-Source Body Diode Characteristi	cs			L				
Continuous source-drain diode current	Is	T _C = 25 °C	-	-	51.6			
Pulse diode forward current	I _{SM}	5	-	-	150	A		
Body diode voltage	V _{SD}	I _S = 5 A, V _{GS} = 0 V	-	0.73	1.1	V		
Body diode reverse recovery time	t _{rr}	5 , 45 -	-	38	76	ns		
Body diode reverse recovery charge	Q _{rr}	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	_	33	66	nC		
Reverse recovery fall time	t _a	$T_{\rm J} = 25 ^{\circ}{\rm C}$	_	20	-	1		
Reverse recovery rise time	t _b	Č		18		ns		

Notes

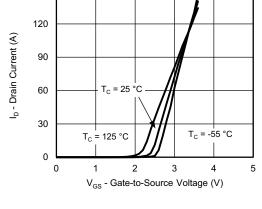
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



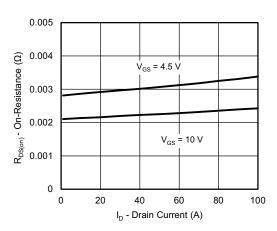


Output Characteristics

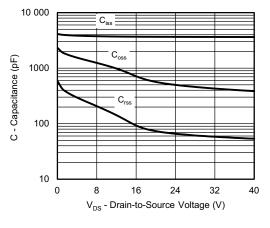


150

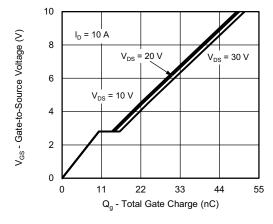
Transfer Characteristics



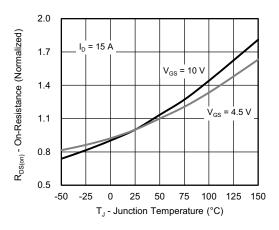
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

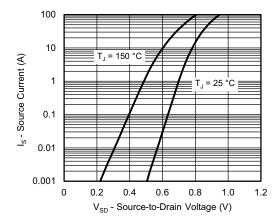


Gate Charge

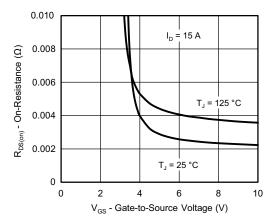


On-Resistance vs. Junction Temperature

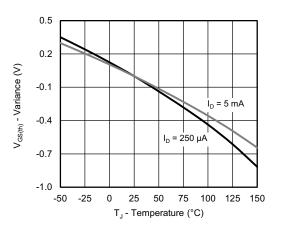




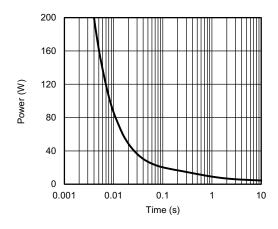
Source-Drain Diode Forward Voltage



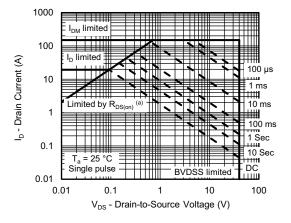
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

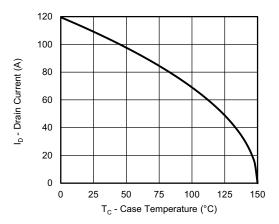


Safe Operating Area, Junction-to-Ambient

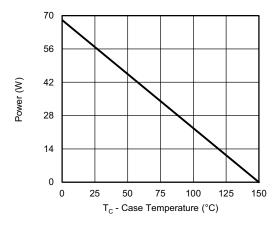
Note

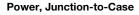
a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

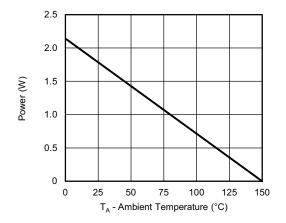




Current Derating a





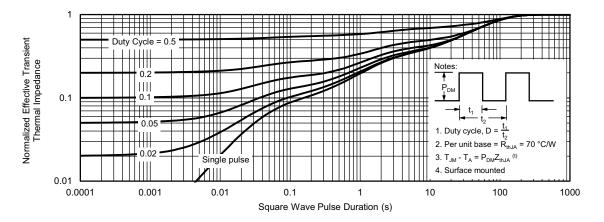


Power, Junction-to-Ambient

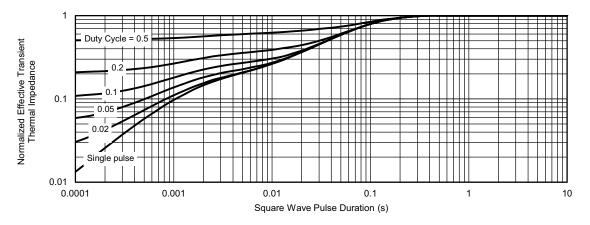
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient

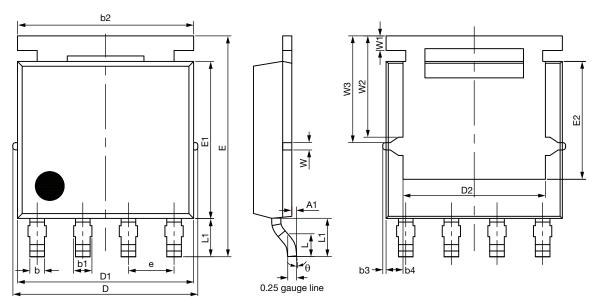


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?76203.

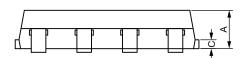


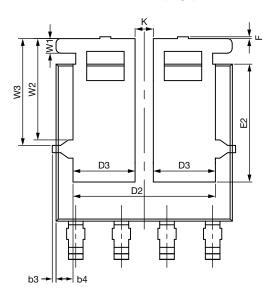
PowerPAK® SO-8L Case Outline 1



Topside view

Backside view (single)





Backside view (dual)



www.vishay.com

Vishay Siliconix

DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	3.18	3.28	3.38	0.125	0.129	0.133	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51		0.020			
W	0.23			0.009			
W1	0.41			0.016			
W2	2.82			0.111			
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

ECN: S19-0643-Rev. E, 05-Aug-2019

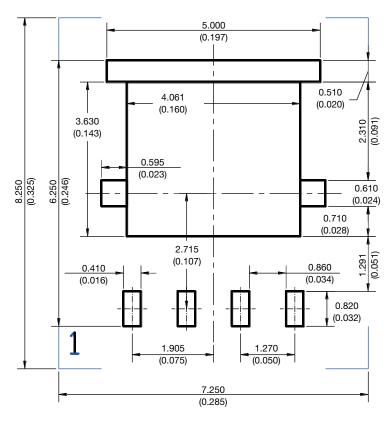
DWG: 5976

Note

• Millimeters will gover



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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